

TEF1001 TRM

Revision v.42
Exported on 2021-03-01

Online version of this document:



1 Table of Contents

1	Table of Contents	2
2	Table of Figures	4
3	Table of Tables	5
4	Overview	6
4.1	Key Features	6
4.2	Block Diagram	6
4.3	Main Components	8
4.4	Initial Delivery State	9
4.5	Control Signals	9
5	Signals, Interfaces and Pins	11
5.1	FMC HPC Connector	11
5.2	PCI Express Interface	14
5.3	JTAG Connectors	15
5.4	FAN Connectors	15
6	On-board Peripherals	17
6.1	System Controller CPLD	17
6.2	DDR3 SDRAM ECC SO-DIMM Socket	21
6.3	Quad SPI Flash Memory	21
6.4	Programmable Clock Generator	22
6.5	Oscillators	23
6.6	On-board LEDs	24
6.7	Configuration DIP-switch	25
6.8	Push Buttons	26
7	Power and Power-On Sequence	27
7.1	Power Consumption	27
7.2	Power Distribution Dependencies	27
7.3	Power-On Sequence	29
7.4	Bank Voltages	31
7.5	Power Rails	31
8	Technical Specifications	33
8.1	Absolute Maximum Ratings	33
8.2	Recommended Operating Conditions	34
8.3	Physical Dimensions	35
9	Variants Currently In Production	37
10	Revision History	38





38
39
39
39
39
39
39
39
39





2 Table of Figures

Figure 1: TEF1001-02 block diagram	7
Figure 2: TEF1001-02 main components	
Figure 3: Power Distribution	28
Figure 4: Power Sequency	30
Figure 5: Physical dimensions drawing	36
Figure 6: Hardware Revision Number	38





3 Table of Tables

Table 1: Initial delivery state of programmable on-board devices	9
Table 2: TEF1001 Control Signals	10
Table 3: FMC connector J2 interfaces	11
Table 4: FMC connector J2 MGT lanes	12
Table 5: FMC connector J2 clock signal input	13
Table 6: FMC connector J2 available VCC/VCCIO	13
Table 7: FMC connector J2 cooling fan	14
Table 8: GTX lanes routed to the PCIe interface	14
Table 9: PCIe reference clock sources	15
Table 10: JTAG interface signals	15
Table 11: FAN connectors	16
Table 12: System Controller CPLD I/O pins	17
Table 13: DDR3 SODIMM socket I ² C interface	21
Table 14: Quad SPI interface signals and connections	21
Table 15: Programmable quad PLL clock generator inputs and outputs	22
Table 16: Reference clock signals	23
Table 17: On-board LEDs description	24
Table 18: DIP-switch S1 functionality description	25
Table 19: On-board Push Button	26
Table 20: Typical power consumption	27
Table 21: Board I/O bank voltages	31
Table 22: Board power rails	31
Table 23: Module absolute maximum ratings	33
Table 24: Recommended Operating Conditions	34
Table 25: Trenz Electronic Shop Overview	37
Table 26: Hardware Revision History	38
Table 27: Document change history	38

Revision: v.42



4 Overview

The Trenz Electronic TEF1001 FPGA board is a PCI Express form factor card integrating the Xilinx Kintex-7 XC7K160T, XC7K325T or XC7K410T FPGA SoC. The FPGA-board is designed for high system resources and intended for use in applications with high demands on system performance and throughput. To extent the board with standard DDR3 SDRAM memory module, there is a 204-pin SODIMM socket with 64bit databus width on the board present. Highspeed data transmission is enabled by the 4 lane PCIe Gen 2 interface.

The board offers a HPC (High Pin Count) ANSI/VITA 57.1 compatible FMC interface connector for standard FPGA Mezzanine cards and modules. Other interface connectors found on-board include JTAG for accessing FPGA and on-board System Controller CPLD.

The TEF1001 FPGA board is intended to be used as add-on card in a PCIe 2.0 or higher capable host system to meet the power supply requirements.

Refer to http://trenz.org/tef1001-info for the current online version of this manual and other available documentation.

4.1 Key Features

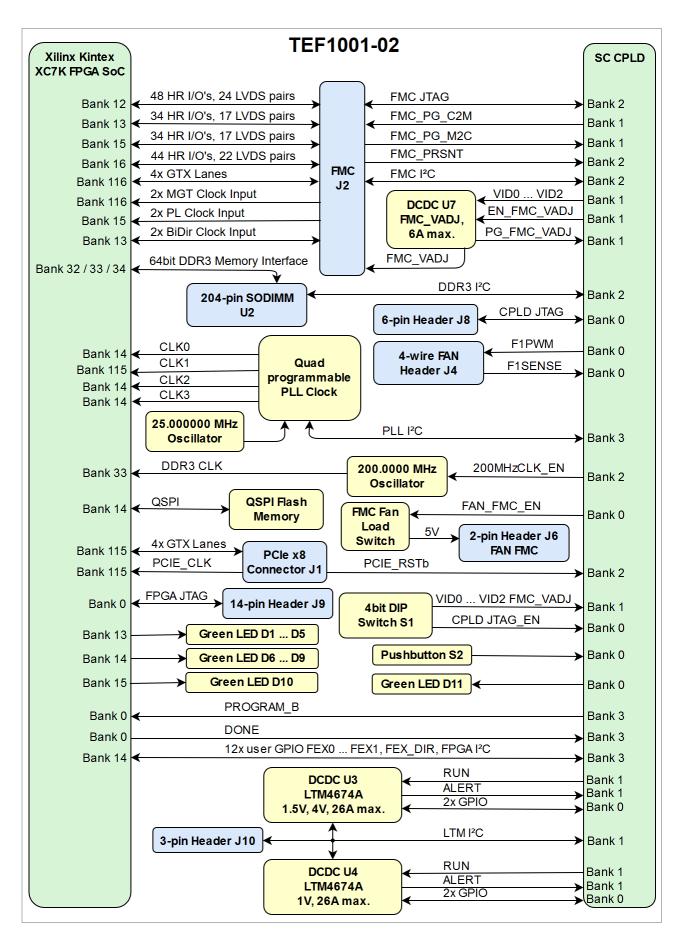
- Xilinx Kintex-7 XC7K160T, XC7K325T or XC7K410T FPGA SoC
- · Large number of configurable I/Os are provided via HPC FMC connector
 - · 4 GTX high-performance transceiver
 - · 2x MGT transceiver clock inputs
 - 160 FPGA I/O's (80 LVDS pairs)
- · On-board high-efficiency switch-mode DC-DC converters
- Lattice MachXO2 LCMXO2-1200HC System Controller CPLD
- 10x User LEDs
- PCI Express x8 connector with 4 lane PCIe Gen 2 interface
- ANSI Vita 57.1 FMC High Pin Count (HPC) connector
- DDR3 SODIMM SDRAM with ECC socket with 64bit databus width
- 256Mbit (32MByte) Quad SPI Flash memory (for configuration and operation) accessible through:
 - FPGA
 - JTAG port (SPI indirect, bus width x4)
- · FPGA configuration through:
 - JTAG connector
 - · Quad SPI Flash memory
- Clocking
 - Si5338 programmable quad PLL clock generator 4 outputs for MGT and PL clocks
 - 200MHz oscillator for DDR3 bank
- System management and power sequencing

Additional assembly options are available for cost or performance optimization upon request.

4.2 Block Diagram









Revision: v.42

Figure 1: TEF1001-02 block diagram

4.3 Main Components

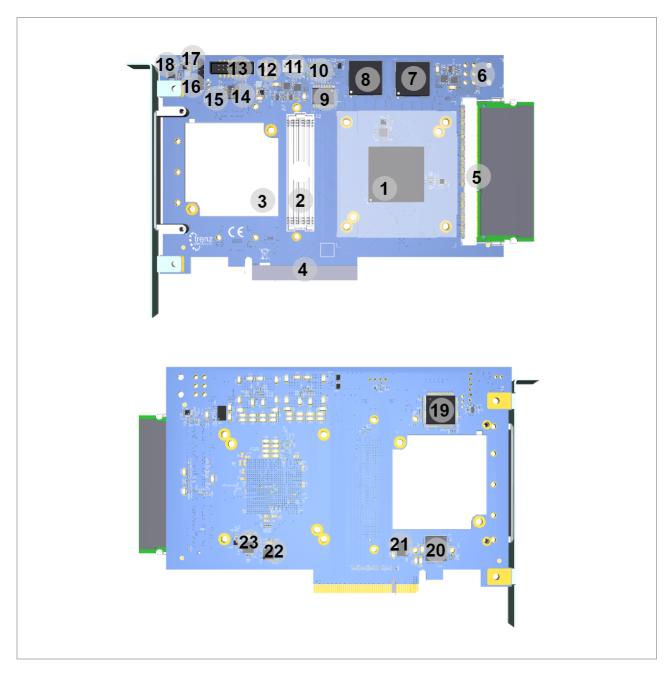


Figure 2: TEF1001-02 main components

- 1. Xilinx Kintex XC7K-2FBG676I FPGA SoC, U6
- 2. ANSI/VITA 57.1 compliant FMC HPC connector, J2
- 3. Cooling fan 5VDC M1 (45X5MM, 0.7W, 1.06CFM), M1
- 4. PCle x8 connector, J1
- 5. DDR3 SODIMM 204-pin socket, U2
- 6. 6-pin 12V power connector, J5
- 7. Step-down DC-DC converter @1.5V and @4V (LT LTM4676A), U3





- 8. Step-down DC-DC converter @1.0V (LT LTM4676A), U4
- 9. 256 Mbit Quad SPI Flash Memory (Micron N25Q256A), U12
- 10. 10x Green user LEDs connected to FPGA, D1 ... D10
- 11. 4-wire PWM fan connector, J4
- 12. User button, S2
- 13. FPGA JTAG connector, J9
- 14. 4bit DIP switch, S1
- 15. I²C header for LTM4676A DC-DC converter, J10
- 16. System Controller CPLD JTAG header, J8
- 17. 1x Green LED connected to SC CPLD, D11
- 18. 2-pin 5V FAN header, J6
- 19. System Controller CPLD (Lattice Semiconductor LCMXO2-1200HC), U5
- 20. 6A PowerSoC DC-DC converter @FMC_VADJ (Altera EN5365QI), U7
- 21. 4A PowerSoC DC-DC converter @3.3V (3V3FMC) (Altera EN6347QI), U15
- 22. LDO converter @1.2V (MGTAVTT_FPGA) (TI TPS74401RGW), U17
- 23. LDO converter @1.0V (MGTAVCC_FPGA) (TI TPS74401RGW), U18
- 24. 4A PowerSoC DC-DC converter @1.8V (Altera EN6347QI), U7

4.4 Initial Delivery State

Storage device name	Content	Notes
Si5338A OTP Area	not programmed	-
SPI Flash OTP Area	Empty, not programmed	Except serial number programmed by flash vendor
SPI Flash Quad Enable bit	Programmed	-
SPI Flash main array	demo design	-
HyperFlash Memory	not programmed	-
eFUSE USER	Not programmed	-
eFUSE Security	Not programmed	-

Table 1: Initial delivery state of programmable on-board devices

4.5 Control Signals

To get started with TEF1001 board, some basic control signals are essential and are described in the following table:





Control signal	Switch / Button / LED / Pin	Signal Schematic Names	Connect ed to	Functionality	Notes
SC CPLD JTAG Enable	DIP switch S1-1	JTAG_EN	SC CPLD U5, pin 82	ON-position: SC CPLD U5 JTAG interface enabled	-
BOOT Mode	FPGA bank 0, pins T5, T2, P5	-	Pin T5 (M0): 1V8 Pin T2 (M1): GND Pin P5 (M2): GND	Hard-wired Boot Mode	By default the configuration mode pins M[2:0] of the FPGA are set to QSPI mode (Master SPI)
Global Reset input	Push Button S2	S2	SC CPLD U5, pin 77	Manual reset from user	-
FMC_VAD J voltage selection	DIP switches S1-2, S1-3, S1-4	VIDO_FMC_V ADJ_CTRL VID2_FMC_V ADJ_CTRL	SC CPLD U5, pins 71, 63, 62	sets adjustable voltage 'FMC_VADJ' for FMC connector	DIP-switch states forwarded by SC CPLD U5 to DC-DC U7. Refer to section Configuration DIP-switch for more details.

Table 2: TEF1001 Control Signals



5 Signals, Interfaces and Pins

5.1 FMC HPC Connector

I/O signals and interfaces connected to the FPGA SoCs I/O bank and FMC connector J2:

Interf aces	I/O Signal Count	LVDS- pairs count	Connected to	VCCO bank Voltage	Notes
I/O	48	24	FPGA Bank 12 HR	FMC_VADJ	Bank voltage FMC_VADJ is supplied by DC-DC
	34	17	FPGA Bank 13 HR	FMC_VADJ	converter U7
	34	17	FPGA Bank 15 HR	FMC_VADJ	
	44	44	FPGA Bank 16 HR	VIO_B_FM C	Bank voltage VIO_B_FMC is supplied by FMC connector J2
I ² C	2	-	SC CPLD U5, Bank 2, pin 48, 49	-	FMC connector J2 is hardware programmed to I ² C address 0x50
JTAG	5	-	SC CPLD U5, Bank 2, pin 27, 28, 331, 32,36	3.3V	4 JTAG pins with additional signal 'TRST'
MGT	-	8 (4 x RX/ TX)	Bank 116 GTX	-	4x MGT lanes
Clock Input	-	2	Bank 116 GTX	_	2x Reference clock input to MGT bank
Contr ol Signal s	3	-	SC CPLD U5, Bank 1, pin 68, 69,70	3.3V	'FMC_PG_C2M', 'FMC_PG_M 2C', 'FMC_PRSNT_M2C_L'

Table 3: FMC connector J2 interfaces

For detailed information about the pin out, please refer to the Pin-out Tables¹.

 $^{{\}tt 1\,https://shop.trenz-electronic.de/de/Download/?path=Trenz_Electronic/Pinout}$



Revision: v.42



FMC connector J2 MGT Lanes:

MGT Lane	Ban k	Typ e	Signal Schematic Name	FMC Connector Pin	FPGA Pin
0	116	GTX	DP3_M2C_PDP3_M2C_NDP3_C2M_PDP3_C2M_N	J2-A10J2-A11J2-A30J2-A31	 MGTXRXP0_116, G4 MGTXRXN0_116, G3 MGTXTXP0_116, F2 MGTXTXN0_116, F1
1	116	GTX	DP2_M2C_PDP2_M2C_NDP2_C2M_PDP2_C2M_N	J2-A6J2-A7J2-A26J2-A27	 MGTXRXP1_116, E4 MGTXRXN1_116, E3 MGTXTXP1_116, D2 MGTXTXN1_116, D1
2	116	GTX	• DP1_M2C_P • DP1_M2C_N • DP1_C2M_P • DP1_C2M_N	J2-A2J2-A3J2-A22J2-A23	 MGTXRXP2_116, C4 MGTXRXN2_116, C3 MGTXTXP2_116, B2 MGTXTXN2_116, B1
3	116	GTX	DP0_M2C_PDP0_M2C_NDP0_C2M_PDP0_C2M_N	J2-C6J2-C7J2-C2J2-C3	 MGTXRXP3_116, B6 MGTXRXN3_116, B5 MGTXTXP3_116, A4 MGTXTXN3_116, A3

Table 4: FMC connector J2 MGT lanes

FMC connector J2 reference clock sources:





Signal Schematic Name	Connecte d to	FMC Connector Pin	FPGA Pin	Notes
• GBTCLK0_M2C_P • GBTCLK0_M2C_N	MGT bank 116	J2-D4 J2-D5	MGTREFCLK0 P_116, D6 MGTREFCLK0 N_116, D5	Supplied by attached FMC module
• GBTCLK1_M2C_P • GBTCLK1_M2C_N	MGT bank 116	J2-B20 J2-B21	MGTREFCLK1 P_116, F6 MGTREFCLK1 N_116, F5	Supplied by attached FMC module

Table 5: FMC connector J2 clock signal input

FMC connector J2 VCC/VCCIO:

Available VCC/ VCCIO	FMC Connector Pin	Source	Notes
3V3FMC	J2-D36 J2-D38 J2-D40 J2-C39	DCDC U15, max. current: 4A	Enable by SC CPLD U5, bank 1, pin 60 Signal: 'EN_3V3FMC'
3V3	J2-D32	LDO U9, max. current: 0.5A	not dedicated for FMC connector
12V	J2-C35 J2-C37	external source through ATX main power connector	-
FMC_VADJ	J2-H40 J2-G39 J2-F40 J2-E39	DCDC U7, max. current: 6A	Enable by SC CPLD U5, bank 1, pin 51 Signal: 'EN_FMC_VADJ' set voltage FMC_VADJ by DIP switch S1

Table 6: FMC connector J2 available VCC/VCCIO







FMC connector J2 Cooling Fan:

Fan Designator	Enable Signal	Notes
M1	Enable by SC CPLD U5, bank 0, pin 78 Signal: 'FAN_FMC_EN'	-

Table 7: FMC connector J2 cooling fan

5.2 PCI Express Interface

The TEF1001 FPGA board is a PCI Express card designed to fit into systems with PCI Express x8 slots and has a data transmission capability which meets PCIe Gen. 2 with 4 GTX lanes routed to the PCIe interface.

Following table lists lane number, MGT bank number, transceiver type, signal schematic name, connector and FPGA pins connection:

Lane	Bank	Туре	Signal Name	PCIe Connector Pin	FPGA Pin
0	115	GTX	PER3_PPER3_NPET3_PPET3_N	J1-A29J1-A30J1-B27J1-B28	MGTXTXP0_115, P2MGTXTXN0_115, P1MGTXRXP0_115, R4MGTXRXN0_115, R3
1	115	GTX	PER2_PPER2_NPET2_PPET2_N	J1-A25J1-A26J1-B23J1-B24	MGTXTXP1_115, M2MGTXTXN1_115, M1MGTXRXP1_115, N4MGTXRXN1_115, N3
2	115	GTX	PER1_PPER1_NPET1_PPET1_N	J1-A21J1-A22J1-B19J1-B20	MGTXTXP2_115, K2MGTXTXN2_115, K1MGTXRXP2_115, L4MGTXRXN2_115, L3
3	115	GTX	PERO_PPERO_NPETO_PPETO_N	J1-A16J1-A17J1-B14J1-B15	MGTXTXP3_115, H2MGTXTXN3_115, H1MGTXRXP3_115, J4MGTXRXN3_115, J3

Table 8: GTX lanes routed to the PCIe interface



TEF1001 TRM Revision: v.42

PCI e	Signal Schematic Name	Connecte d to	PCIe connector pin	FPGA Pin	Notes
J1	PCIE_CLK_P PCIE_CLK_N	MGT bank 115	J1-A13, REFCLK+ J1-A14, REFCLK-	MGTREFCLK 1P_115, K6 MGTREFCLK 1N_115, K5	External clock supplied by PCIe interface

Table 9: PCIe reference clock sources

5.3 JTAG Connectors

There are two JTAG connectors J8 and J9 available on the TEF1001 board:

JTAG Interface	Signal Schematic Name	JTAG Connector Pin	Connected to
CPLD JTAG	CPLD_JTAG_TMS	J8-1	SC CPLD, bank 0, pin 90
VCCIO: 3.3V	CPLD_JTAG_TDI	J8-2	SC CPLD, bank 0, pin 94
Connector: J8	CPLD_JTAG_TDO	J8-3	SC CPLD, bank 0, pin 95
	CPLD_JTAG_TCK	J8-4	SC CPLD, bank 0, pin 91
FPGA JTAG	FPGA_JTAG_TMS	J9-4	FPGA, bank 0, pin N9
VCCIO: 1.8V	FPGA_JTAG_TCK	J9-6	FPGA, bank 0, pin M8
Connector: J9	FPGA_JTAG_TDO	J9-8	FPGA, bank 0, pin N8
	FPGA_JTAG_TDI	J9-10	FPGA, bank 0, pin L8

Table 10: JTAG interface signals

5.4 FAN Connectors

The TEF1001 board offers one FAN connector for cooling the FPGA device and one built-in FAN for the FMC modules.





Connector	Signal Schematic Names	Connected to	Notes
4-Wire PWM FAN connector J4, 12V power supply	'F1SENSE', pin J4-3 'F1PWM', pin J4-4	SC CPLD U5, pin 99 SC CPLD U5, pin 98	FPGA cooling FAN can be controlled via I ² C interface from FPGA, see current SC CPLD firmware
2-pin FAN connector J6, 5V power supply with TPS2051 Load Switch U25	'FAN_FMC_EN', (Load Switch U25, pin 4)	SC CPLD U5, pin 78	FMC cooling FAN

Table 11: FAN connectors



6 On-board Peripherals

6.1 System Controller CPLD

The System Controller CPLD (U5) is provided by Lattice Semiconductor LCMXO2-256HC (MachXO2 Product Family). The SC-CPLD is the central system management unit where essential control signals are logically linked by the implemented logic in CPLD firmware, which generates output signals to control the system, the on-board peripherals and the interfaces. Interfaces like JTAG and I^2 C between the on-board peripherals and to the FPGA module are by-passed, forwarded and controlled by the System Controller CPLD.

Other tasks of the System Controller CPLD are the monitoring of the power-on sequence and to display the programming state of the FPGA module.

For detailed function of the pins and signals, the internal signal assignment and the implemented logic, look to the Wiki reference page² of the board's SC CPLD or into its bitstream file.. Table below lists the SC CPLD I/O pins with their default configuration:

SC CPLD U5 Pins and Interfaces	Connected to	Function	Notes	
200MHZCLK_EN	Oscillator U1, pin 1	Oscillator U1 control line	enables 200.0000MHz oscillator U1	
BUTTON	Push Button S2	user	Reset Button	
CPLD_JTAG_TDO	header J8, pin	interface	SC CPLD JTAG interface enabled when	
CPLD_JTAG_TDI	header J8, pin 2		DIP-switch S1-1 in ON- position	
CPLD_JTAG_TCK	header J8, pin 4			
CPLD_JTAG_TMS	header J8, pin			
JTAG_EN	DIP switch S1-1			
DDR3_SCL	SO-DIMM U2. pin 202	I ² C bus of DDR3 SO-DIMM	I ² C interface connected to FPGA	
DDR3_SDA	SO-DIMM U2. pin 200			

² https://wiki.trenz-electronic.de/display/PD/TEF1001-REV01+CPLD



SC CPLD U5 Pins and Interfaces	Connected to	Function	Notes	
PLL_SCL	Si5338 U13, pin 12	I ² C bus of SI5338 quad clock PLL	I ² C interface connected to FPGA	
PLL_SDA	Si5338 U13, pin 19			
PCIE_RSTb	PCle J1, pin A11	PCIe reset input	refer to current SC CPLD firmware for functionality	
FEX_DIR / FEX0 FEX11	FPGA bank 14	user GPIO	refer to current SC CPLD firmware for functionality	
F1PWM	FAN connector J4, pin 4	FPGA FAN control	refer to current SC CPLD firmware for functionality	
F1SENSE	FAN connector J4, pin 3			
FAN_FMC_EN	Load Switch U25, pin 4	FMC FAN enable		
FMC_PG_C2M	FMC J2, pin D1	FMC control	refer to current SC CPLD firmware for functionality	
FMC_PG_M2C	FMC J2, pin F1	signals		
FMC_PRSNT_M2C_L	FMC J2, pin H2			
FMC_SCL	FMC J2, pin C30	FMC I ² C	I ² C connected to FPGA	
FMC_SDA	FMC J2, pin C31			
FMC_TCK	FMC J2, pin D29	FMC JTAG	refer to current SC CPLD firmware for functionality	
FMC_TDI	FMC J2, pin D30			
FMC_TDO	FMC J2, pin D31			
FMC_TMS	FMC J2, pin D33			



SC CPLD U5 Pins and Interfaces	Connected to	Function	Notes
FMC_TRST	FMC J2, pin D34		
DONE	FPGA bank 0, pin J7	FPGA configuration	PL configuration completed
PROGRAM_B	FPGA bank 0, pin P6	signal	PL configuration reset signal
LED1	Green LED D11	LED status signal	refer to current SC CPLD firmware for functionality
FPGA_IIC_OE	FPGA bank 14, pin F25	SC CPLD works as I ² C switch	I ² C output enable
FPGA_IIC_SCL	FPGA bank 14, pin G26	with the FPGA as I ² C-Master and on-board	I ² C clock line
FPGA_IIC_SDA	FPGA bank 14, pin G25	peripherals as I ² C-Slaves	I ² C data line
EN_1V8	DC-DC U20, pin 27	Power control	enable signal DC-DC U20
PG_1V8	DC-DC U20, pin 28		power good signal DC-DC U20
EN_3V3FMC	DC-DC U15, pin 27		enable signal DC-DC U15
PG_3V3	DC-DC U15, pin 28		power good signal DC-DC U15
EN_FMC_VADJ	DC-DC U7, pin 52		enable signal DC-DC U7
PG_FMC_VADJ	DC-DC U7, pin 46		power good DC-DC U7
VID0_FMC_VADJ, VID1_FMC_VADJ, VID2_FMC_VADJ	DC-DC U7, pin 45, 44, 43		DCDC U7 power selection pin





SC CPLD U5 Pins and Interfaces	Connected to	Function	Notes
VID0_FMC_VADJ_CT RL, VID1_FMC_VADJ_CT RL, VID2_FMC_VADJ_CT RL	DIP switch S1-2, DIP switch S1-3, DIP switch S1-4		Power selection of FMC_VADJ, forwarded to DCDC U7
LTM_1V5_RUN	DC-DC U3, pin F5		enable signals of DCDC U3, U4 (LTM4676) refer to current SC CPLD
LTM_4V_RUN	DC-DC U3, pin F5		firmware for functionality
LTM_SCL	DC-DC U3 / U4, pin E6	DCDC U3, U4 (LTM4676) I ² C	I ² C Address U3: 0x40 I ² C Address U4: 0x4F I ² C interface of LTM4676 ICs also accessible through header J10
LTM_SDA	DC-DC U3 / U4, pin D6		
LTM1_ALERT	DC-DC U4, pin E5	DCDC U3, U4 (LTM4676) control,	refer to current SC CPLD firmware for functionality
LTM2_ALERT	DC-DC U3, pin E5	active low	
LTM_1V_IO0	DC-DC U4, pin E4		
LTM_1V_IO1	DC-DC U4, pin F5		
LTM_1V5_4V_IO0	DC-DC U3, pin E4		
LTM_1V5_4V_IO1	DC-DC U3, pin F4		

Table 12: System Controller CPLD I/O pins

TEF1001 TRM Revision: v.42

6.2 DDR3 SDRAM ECC SO-DIMM Socket

The TEF1001 board supports additional DDR3 **ECC** SO-DIMM via 204-pin socket U2. The DDR3 memory interface has a 64bit wide databus and is routed to the FPGA banks 32, 33 and 34.

The reference clock signal for the DDR3 interface is generated by the 200.0000MHz MEMS oscillator U1 and is applied to the FPGA bank 33.

There is also a I²C interface between the System Controller CPLD U5 and the DDR3 ECC SO-DIMM memory socket II2

I ² C Interface	Schematic net names	Connected to	I ² C Address	Notes
DDR3 SODIMM, U2	'DDR3_SDA', pin 200 'DDR3_SCL', pin 202	SC CPLD U5, pin 42 SC CPLD U5, pin 43	module dependent	-

Table 13: DDR3 SODIMM socket I2C interface

(i) It is important to use SO-DIMMs which provide ECC functionality. SO-DIMMs without ECC are not compatible with this board.

6.3 Quad SPI Flash Memory

A 256 Mbit (32 MByte) Quad SPI Flash Memory (Micron N25Q256A, U12) is provided for FPGA configuration file storage. After configuration process completes the remaining free memory can be used for application data storage. All four SPI data lines are connected to the FPGA allowing x1, x2 or x4 data bus widths to be used. The maximum data transfer rate depends on the bus width and clock frequency. The memory can be accessed indirectly by the FPGA JTAG port (J9) by implementing the functional logic for this purpose inside the FPGA.

Quad SPI Flash memory interface is connected to the FPGA bank 14, QSPI clock is provided by FPGA config bank 0.

Signal Name	QSPI Flash Memory U12 Pin	FPGA Pin
FLASH_QSPI_CS	S, Pin 7	Bank 14, Pin C23
FLASH_QSPI_D00	DQ0, Pin 15	Bank 14, Pin B24
FLASH_QSPI_D01	DQ1, Pin 8	Bank 14, Pin A25
FLASH_QSPI_D02	DQ2, Pin 9	Bank 14, Pin B22
FLASH_QSPI_D03	DQ3, Pin 1	Bank 14, Pin A22
FPGA_CFG_CCLK	C, Pin 16	Bank 0, Pin C8

Table 14: Quad SPI interface signals and connections





A SPI Flash QE (Quad Enable) bit must be set to high or FPGA is unable to load its configuration from flash during power-on. By default this bit is set to high at the manufacturing plant.

6.4 Programmable Clock Generator

There is a Silicon Labs I²C programmable quad PLL clock generator on-board (Si5338A, U13) to generate various reference clocks for the module.

Si5338A Pin	Signal Name / Description	Connected to	Direction	Note
IN1	-	not connected	Input	not used
IN2	-	GND	Input	not used
IN3	Reference input clock	U3, pin 3	Input	25.000000 MHz oscillator U14, Si8208AI
IN4	-	GND	Input	I ² C slave device address LSB
IN5	-	not connected	Input	not used
IN6	-	GND	Input	not used
SCL	PLL_SCL	SC CPLD U5, pin 8	Input / Output	I ² C interface muxed to FPGA
SDA	PLL_SDA	SC CPLD U5, pin 2	Input / Output	Slave address: 0x70.
CLKOA	CLK0_P	U6, G24	Output	Clock to PL bank 14
CLK0B	CLK0_N	U6, F24		
CLK1A	MGTCLK_5338_P	U6, H6	Output	Clock to MGT bank 115,
CLK1B	MGTCLK_5338_N	U6, H5		AC decoupled
CLK2A	CLK1_P	U6, G22	Output	Clock to PL bank 14
CLK2B	CLK1_N	U6, F23		



Revision: v.42

Si5338A Pin	Signal Name / Description	Connected to	Direction	Note
CLK3A	CLK2_P	U6, D23	Output	Clock to PL bank 14
CLK3B	CLK2_N	U6, D24		

Table 15: Programmable quad PLL clock generator inputs and outputs

6.5 Oscillators

The FPGA module has following reference clocking sources provided by on-board oscillators and FMC connector J2:

Clock Source	Frequenc y	Signal Schematic Name	Clock Destination	Notes
U14, SiT8208AI	25.000000 MHz	CLK	Si5338A PLL U13, pin 3 (IN3)	-
U1, DSC1123DL	200.0000 MHz	DDR3_CLK_P	FPGA bank 33, pin AB11	Enable by SC CPLD U5, pin 30
5		DDR3_CLK_N	FPGA bank 33, pin AC11	Signal: '200MHzCLK_EN'
FMC Connector	Connector	GBTCLK0_M2C_P, Pin J2-D4	FPGA bank 116, pin D6	reference clock to MGT bank 116
J2		GBTCLK0_M2C_N, Pin J2-D5	FPGA bank 116, pin D5	
	-	GBTCLK1_M2C_P, Pin J2-B20	FPGA bank 116, pin F6	reference clock to MGT bank 116
		GBTCLK1_M2C_N, Pin J2-B21	FPGA bank 116, pin F5	
	-	CLK0_M2C_P, Pin J2-H4	FPGA bank 15, pin H17	reference clock to PL bank 15
		CLK0_M2C_N, Pin J2-H5	FPGA bank 15, pin H18	
	-	CLK1_M2C_P, Pin J2-G2	FPGA bank 15, pin G17	reference clock to PL bank 15



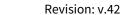


Clock Source	Frequenc y	Signal Schematic Name	Clock Destination	Notes
		CLK1_M2C_N, Pin J2-G3	FPGA bank 15, pin G18	
	-	CLK2_BIDIR_P, Pin J2-K4	FPGA bank 13, pin P23	reference clock to PL bank 13
-	CLK2_BIDIR_N, Pin J2-K5	FPGA bank 13, pin N23	bidirectional clock line	
	-	CLK3_BIDIR_P, Pin J2-J2	FPGA bank 13, pin R22	reference clock to PL bank 13
		CLK3_BIDIR_N, Pin J2-J3	FPGA bank 13, pin R23	bidirectional clock line

Table 16: Reference clock signals

6.6 On-board LEDs

LE D	Colo r	Signal Schematic name	Connected to	Description and Notes
D1	Gree n	FPGA_LED1_VT	FPGA bank 13, pin K25	LEDs D1 to D10 are available to user.
D2	Gree n	FPGA_LED2_VT	FPGA bank 13, pin K26	LED voltages are translated from FPGA bank 13 and 14
D3	Gree n	FPGA_LED3_VT	FPGA bank 13, pin P26	VCCO voltage FMC_VADJ to 3V3.
D4	Gree n	FPGA_LED4_VT	FPGA bank 13, pin R26	
D5	Gree n	FPGA_LED5_VT	FPGA bank 13, pin N16	
D6	Gree n	FPGA_LED6_VT	FPGA bank 14, pin J26	
D7	Gree n	FPGA_LED7_VT	FPGA bank 14, pin H26	







LE D	Colo r	Signal Schematic name	Connected to	Description and Notes
D8	Gree n	FPGA_LED8_VT	FPGA bank 14, pin E26	
D9	Gree n	FPGA_LED9_VT	FPGA bank 14, pin A24	
D1 0	Gree n	FPGA_LED10_VT	FPGA bank 15, pin F19	
D1 1	Gree n	LED1	System Controller CPLD, bank 0, pin 76	refer to current CPLD firmware for LED functionality

Table 17: On-board LEDs description

6.7 Configuration DIP-switch

There is one 4-bit DIP-witches S1 present on the TEB0911 board to configure options and set parameters. The following section describes the functionalities of the particular switches.

Table below describes the functionalities of the switches of DIP-switches S3 and S4 at their each positions:

DIP- switch S3	Signal Schematic Name	Connected to	Functionality	Notes
S1-1	JTAG_EN	SC CPLD U5, bank 1, pin 82	enables JTAG interface of SC CPLD U5 in ON-position	SC CPLD programmable through JTAG header J8







DIP- switch S3	Signal Schematic Name	Connected to	Functionality	Notes
S1-2	VIDO_FMC_VA DJ_CTRL	SC CPLD U5, bank 1, pin 71	set 3bit code to adjust FMC_VADJ voltage	The FMC_VADJ voltage is provided by
S1-3	VID1_FMC_VA DJ_CTRL	SC CPLD U5, bank 1, pin 63		the voltage can be
S1-4	VID2_FMC_VA DJ_CTRL	SC CPLD U5, bank 1, pin 62		adjusted from 0.8V to 3.3V in 7 steps: Set DIP-switches as bit pattern "S1-4 S1-3 S1-2: FMC_VADJ": 0 0 0 : 3.3V

Table 18: DIP-switch S1 functionality description

6.8 Push Buttons

There is one push buttons available to the user connected to the SC CPLD U5:

Button	Connected to	Function	Notes
S2	SC CPLD U5, pin 77	Global board Reset	Refer to documentation of current SC CPLD firmware for more detais.

Table 19: On-board Push Button

TEF1001 TRM Revision: v.42

7 Power and Power-On Sequence

7.1 Power Consumption

The maximum power consumption of a module mainly depends on the design running on the FPGA.

Xilinx provide a power estimator excel sheets to calculate power consumption. It's also possible to evaluate the power consumption of the developed design with Vivado. See also Trenz Electronic Wiki FAQ³.

Power Input	Typical Current
12V VIN	TBD*

Table 20: Typical power consumption

It is recommended to connect the ATX connector J5 to a 12V power supply source with minimum current capability of 6A to provide a sufficient power source to the board. Only one power source is needed at the same time, the system disconnects automatically PCIe power supply from PCIe edge connector J1 if the board is powered by the ATX connector J5.



To avoid any damage to the module, check for stabilized on-board voltages should be carried out (i.e. power good and enable signals) before powering up any FPGA's I/O bank voltages VCCO_x. All I/Os should be tri-stated during power-on sequence.

7.2 Power Distribution Dependencies

^{*} TBD - To Be Determined soon with reference design setup.

³ https://wiki.trenz-electronic.de/display/PD/FAQ



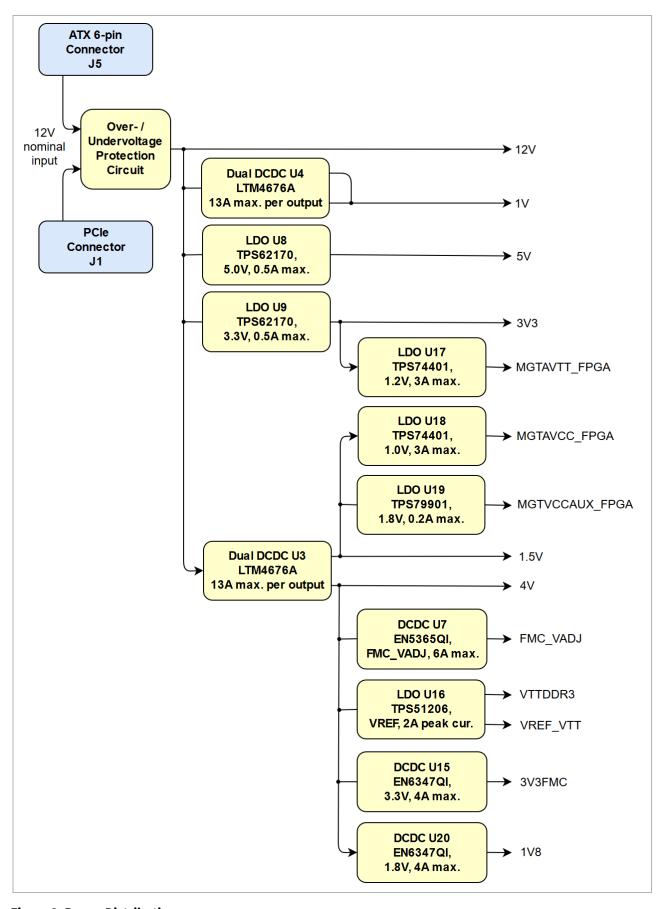


Figure 3: Power Distribution

TEF1001 TRM Revision: v.42

7.3 Power-On Sequence

The TEF1001 board meets the recommended criteria to power up the Xilinx FPGA properly by keeping a specific sequence of enabling the on-board DC-DC converters dedicated to the particular functional units of the FPGA chip and powering up the on-board voltages.

Some of the voltages are handled by the System Controller CPLD using "Power good"-signals from the voltage regulators:

Following diagram clarifies the sequence of enabling the particular on-board voltages, which will power-up in descending order as listed in the blocks of the diagram:



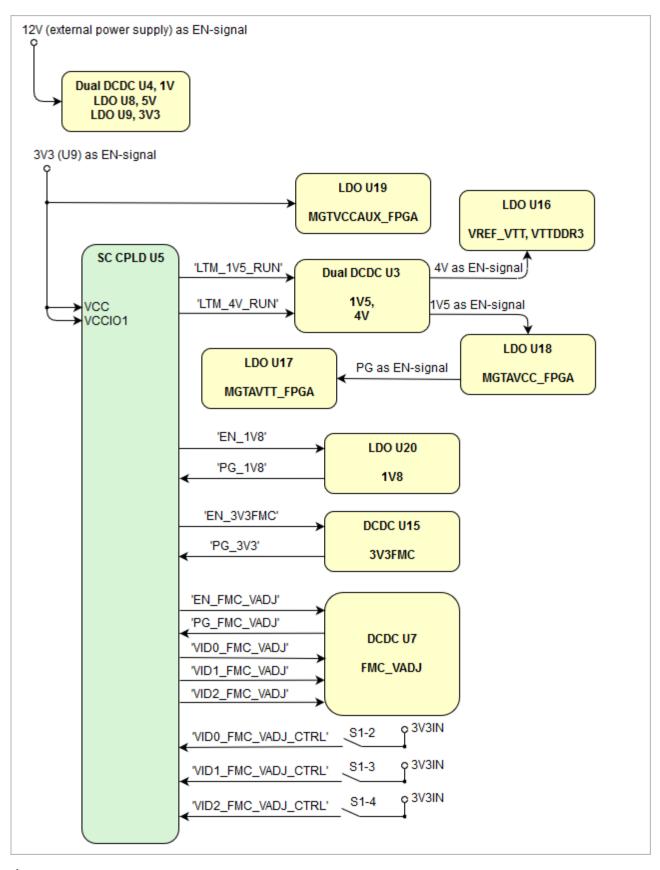


Figure 4: Power Sequency



7.4 Bank Voltages

Ban k	Schematic Name	Voltag e	Range	Notes
0	1V8	1.8V	-	Config bank 0 fixed to 1.8V
12	FMC_VADJ	user	HR: 1.2V to 3.3V	FMC_VADJ voltage ajustable by DIP switch S1
13	FMC_VADJ	user	HR: 1.2V to 3.3V	FMC_VADJ voltage ajustable by DIP switch S1
14	1V8	1.8V	HR: 1.2V to 3.3V	PL bank 14 fixed to 1.8V
15	FMC_VADJ	user	HR: 1.2V to 3.3V	FMC_VADJ voltage ajustable by DIP switch S1
16	VIO_B_FMC	user	HR: 1.2V to 3.3V	PL bank 16 fixed to 1.8V
32	1V5	1.5V	HP: 1.2V to 1.8V	DDR3 memory interface
33	1V5	1.5V	HP: 1.2V to 1.8V	DDR3 memory interface
34	1V5	1.5V	HP: 1.2V to 1.8V	DDR3 memory interface
115 116	MGTAVCC_FPGA MGTVCCAUX_FP GA MGTAVTT_FPGA	1.0V 1.8V 1.2V	MGT bank supply voltage MGT bank auxiliary supply voltage MGT bank termination circuits voltage	MGT banks with Xilinx GTX transceiver units

Table 21: Board I/O bank voltages

7.5 Power Rails

Connector / Pin	Voltage	Direction	Notes
J4, pin 2	12V	Output	4-wire PWM fan connector supply voltage





Connector / Pin	Voltage	Direction	Notes
J6, pin 2	5V	Output	Cooling fan M1 supply voltage
J8, pin 6	3V3	Output	VCCIO CPLD JTAG
J9, pin 2	1V8	Output	VCCIO FPGA JTAG
J2, pin C35 / C37	12V	Output	FMC supply voltage
J2, pin D32	3V3	Output	VCCIO FMC
J2, pin D36 / D38 / D39 / D40	3V3FMC	Output	VCCIO FMC
J2, pin H1	VREF_A_M 2C	Input	VREF voltage for bank 13 / 15
J2, pin K1	VREF_B_M 2C	Input	VREF voltage for bank 16
J2, pin J39 / J40	VIO_B_FM C	Input	PL I/O voltage bank 16 (VCCO)
J2, pin H40 / G39 / F40 / E39	FMC_VADJ	Output	PL I/O voltage bank 12 / 13 / 15 (VCCO)
J1, pin B1 / B2 / B3 / A2 / A3	12V_input _B	Input	12V main power supply from PCIe connector
J5, pin 1 / 2 / 3	12V_input _A	Input	Main power supply connector

Table 22: Board power rails



8 Technical Specifications

8.1 Absolute Maximum Ratings

Parameter	Min	Max	Uni ts	Reference Document
VIN supply voltage	-0.3	20	V	TPS6217 datasheet Note: voltage limitations are not valid for connected FMC module and/or FPGA FAN
Supply voltage for HR I/O banks (VCCO)	-0.5 00	3.600	V	Xilinx datasheet DS182
Supply voltage for HP I/O banks (VCCO)	-0.5 00	2.000	V	Xilinx datasheet DS182
I/O input voltage for HR I/ O banks	-0.5 00	VCCO + 0.500	V	Xilinx datasheet DS182
I/O input voltage for HP I/ O banks	-0.5 00	VCCO + 0.500	V	Xilinx datasheet DS182
Reference Voltage pin (VREF)	-0.5 00	2	V	Xilinx datasheet DS182
Differential input voltage	-0.5	2.625	V	Xilinx datasheet DS182
I/O input voltage for SC CPLD U5	-0.5	3.75	V	Lattice MachXO2 Family datasheet
GTX transceiver reference clocks absolute input voltage	-0.5 00	1.320	V	Xilinx datasheet DS182



TEF1001 TRM Revision: v.42

Parameter	Min	Мах	Uni ts	Reference Document
GTX transceiver receiver (RXP/RXN) and transmitter (TXP/TXN) absolute input voltage	-0.5 00	1.260	V	Xilinx datasheet DS182
Voltages on LTM4676 I ² C pins (LTM_SCL, LTM_SDA), header J10	-0.3	5.5	V	LTM4676A datasheet
Storage temperature	-40	+100	°C	SML-P11 LED datasheet

Table 23: Module absolute maximum ratings



⚠ Assembly variants for higher storage temperature range are available on request.

8.2 Recommended Operating Conditions

Parameter	Min	Max	Uni ts	Reference Document
VIN supply voltage	11.4	12.6	V	12V nominal, ANSI/VITA 57.1 power specification for FMC connector
Supply voltage for HR I/O banks (VCCO)	1.14 0	3.465	V	Xilinx datasheet DS182
Supply voltage for HP I/O banks (VCCO)	1.14 0	1.890	V	Xilinx datasheet DS182
I/O input voltage for HR I/ O banks	-0.5 00	VCCO + 0.20	V	Xilinx datasheet DS182
I/O input voltage for HP I/ O banks	-0.5 00	VCCO + 0.20	V	Xilinx datasheet DS182
Differential input voltage	-0.2	2.625	V	Xilinx datasheet DS182



TEF1001 TRM Revision: v.42

Parameter	Min	Мах	Uni ts	Reference Document
I/O input voltage for SC CPLD U5	-0.3	3.6	V	Lattice MachXO2 Family datasheet
Voltages on LTM4676 I ² C pins (LTM_SCL, LTM_SDA), header J10	0	3.3V	V	LTM4676A datasheet
Board Operating Temperature Range ^{1), 2)}	-40	85	°C	board operating temperature range limited by FPGA SoC and on-board peripherals

Table 24: Recommended Operating Conditions

- 1) Temperature range may vary depending on assembly options
- 2) The operating temperature range of the FPGA soC and on-board peripherals are junction and also ambient operating temperature ranges

Board operating temperature range depends also on customer design and cooling solution. Please contact us for options.



⚠ Please check also Xilinx datasheet DS182⁴ for complete list of absolute maximum and recommended operating ratings.

8.3 Physical Dimensions

⁴ https://www.xilinx.com/support/documentation/data_sheets/ds182_Kintex_7_Data_Sheet.pdf

Revision: v.42

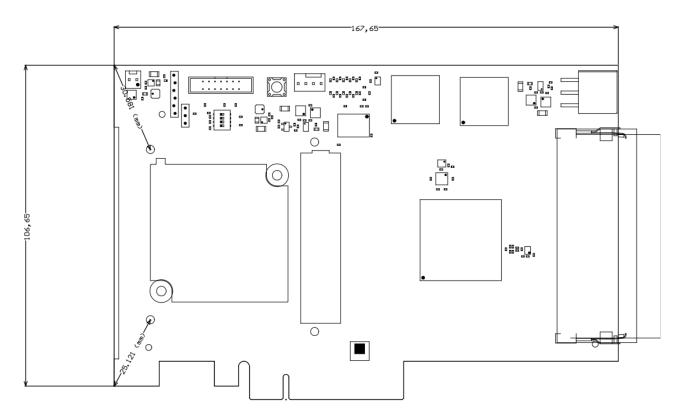


Figure 5: Physical dimensions drawing





9 Variants Currently In Production

Trenz shop TEF1001 overview page				
English page⁵	German page ⁶			

Table 25: Trenz Electronic Shop Overview

⁵ https://shop.trenz-electronic.de/en/Products/Trenz-Electronic/TEF1001-Kintex-7/6 https://shop.trenz-electronic.de/de/Produkte/Trenz-Electronic/TEF1001-Kintex-7/

TEF1001 TRM Revision: v.42

10 Revision History

10.1 Hardware Revision History

Date	Revision	Notes	PCN	Documentation Link
-	02	current available board revision	-	-
-	01	First production release	PCN-20180524 TEF1001-01 ⁷	TEF1001-01 ⁸

Table 26: Hardware Revision History

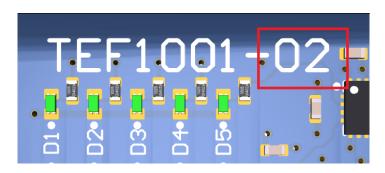


Figure 6: Hardware Revision Number

Hardware revision number can be found on the PCB board together with the module model number separated by the dash.

10.2 Document Change History

Date	Revision	Authors	Description
2018-12-11	v.42(see page 6)	Pedram Babakhani ⁹	update picture
2018-10-24	v.41	Guillermo Herrera	Initial document

Table 27: Document change history

⁷ https://wiki.trenz-electronic.de/pages/viewpage.action?pageId=54397005 8 https://shop.trenz-electronic.de/Download/?path=Trenz_Electronic/PCIe_Cards/TEF1001/REV01

⁹ https://wiki.trenz-electronic.de/display/~P.Babakhani

M Revision: v.42

11 Disclaimer

11.1 Data Privacy

Please also note our data protection declaration at https://www.trenz-electronic.de/en/Data-protection-Privacy

11.2 Document Warranty

The material contained in this document is provided "as is" and is subject to being changed at any time without notice. Trenz Electronic does not warrant the accuracy and completeness of the materials in this document. Further, to the maximum extent permitted by applicable law, Trenz Electronic disclaims all warranties, either express or implied, with regard to this document and any information contained herein, including but not limited to the implied warranties of merchantability, fitness for a particular purpose or non infringement of intellectual property. Trenz Electronic shall not be liable for errors or for incidental or consequential damages in connection with the furnishing, use, or performance of this document or of any information contained herein.

11.3 Limitation of Liability

In no event will Trenz Electronic, its suppliers, or other third parties mentioned in this document be liable for any damages whatsoever (including, without limitation, those resulting from lost profits, lost data or business interruption) arising out of the use, inability to use, or the results of use of this document, any documents linked to this document, or the materials or information contained at any or all such documents. If your use of the materials or information from this document results in the need for servicing, repair or correction of equipment or data, you assume all costs thereof.

11.4 Copyright Notice

No part of this manual may be reproduced in any form or by any means (including electronic storage and retrieval or translation into a foreign language) without prior agreement and written consent from Trenz Electronic.

11.5 Technology Licenses

The hardware / firmware / software described in this document are furnished under a license and may be used / modified / copied only in accordance with the terms of such license.

11.6 Environmental Protection

To confront directly with the responsibility toward the environment, the global community and eventually also oneself. Such a resolution should be integral part not only of everybody's life. Also enterprises shall be conscious of their social responsibility and contribute to the preservation of our common living space. That is why Trenz Electronic invests in the protection of our Environment.

11.7 REACH, RoHS and WEEE

REACH



TEF1001 TRM Revision: v.42

Trenz Electronic is a manufacturer and a distributor of electronic products. It is therefore a so called downstream user in the sense of REACH¹⁰. The products we supply to you are solely non-chemical products (goods). Moreover and under normal and reasonably foreseeable circumstances of application, the goods supplied to you shall not release any substance. For that, Trenz Electronic is obliged to neither register nor to provide safety data sheet. According to present knowledge and to best of our knowledge, no SVHC (Substances of Very High Concern) on the Candidate List¹¹ are contained in our products. Furthermore, we will immediately and unsolicited inform our customers in compliance with REACH - Article 33 if any substance present in our goods (above a concentration of 0,1 % weight by weight) will be classified as SVHC by the European Chemicals Agency (ECHA)¹².

RoHS

Trenz Electronic GmbH herewith declares that all its products are developed, manufactured and distributed RoHS compliant.

WEEE

Information for users within the European Union in accordance with Directive 2002/96/EC of the European Parliament and of the Council of 27 January 2003 on waste electrical and electronic equipment (WEEE).

Users of electrical and electronic equipment in private households are required not to dispose of waste electrical and electronic equipment as unsorted municipal waste and to collect such waste electrical and electronic equipment separately. By the 13 August 2005, Member States shall have ensured that systems are set up allowing final holders and distributors to return waste electrical and electronic equipment at least free of charge. Member States shall ensure the availability and accessibility of the necessary collection facilities. Separate collection is the precondition to ensure specific treatment and recycling of waste electrical and electronic equipment and is necessary to achieve the chosen level of protection of human health and the environment in the European Union. Consumers have to actively contribute to the success of such collection and the return of waste electrical and electronic equipment. Presence of hazardous substances in electrical and electronic equipment results in potential effects on the environment and human health. The symbol consisting of the crossed-out wheeled bin indicates separate collection for waste electrical and electronic equipment.

Trenz Electronic is registered under WEEE-Reg.-Nr. DE97922676.

2019-06-07

¹⁰ http://guidance.echa.europa.eu/

¹¹ https://echa.europa.eu/candidate-list-table

¹² http://www.echa.europa.eu/